



PK592 (v1.0) February 1, 2013

100% Material Declaration Data Sheet for 7 Series FGG676 Package

Average Weight: 2.9810 g

Component	Substance Description	CAS Number or Description	Percentage of Component	Use in Product	Component Weight/ Substance Weight (grams)	Component Percent of Total
Silicon Die					0.048068	1.612
	Silicon	7440-21-3	100.00		0.048068	
Die Attach					0.008755	0.294
	Silver	7440-22-4	77.50		0.006785	
	Bismaleimide monomer	Trade Secret	15.00		0.001313	
	Acrylate monomer	Trade Secret	7.50		0.000657	
Mold Compound					1.497385	50.231
	Epoxy Resin	Trade secret	5.00		0.074869	
	Phenol Resin	Trade secret	3.00		0.044922	
	Phenol Novolac	9003-35-4	3.00		0.044922	
	Metal Hydroxide	Trade Secret	3.00		0.044922	
	Carbon black	1333-86-4	0.30		0.004492	
	Silica fused	60676-86-0	70.40		1.054158	
	Silica Dioxide	7631-86-9	15.00		0.224608	
	Silica, crystalline	14808-60-7	0.30		0.004492	
Copper Wire					0.007404	0.248
	Copper	7440-50-8	98.20		0.007271	
	Palladium	7440-05-3	1.80		0.000133	
Solder Ball					0.564707	18.944
	Tin	7440-31-5	96.50		0.544942	
	Silver	7440-22-4	3.00		0.016941	
	Copper	7440-50-8	0.50		0.002824	

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Substrate					0.854681	28.671
	Copper	7440-50-8	18.90		0.161535	
	Nickel	7440-02-0	6.80		0.058118	
	Gold	7440-57-5	0.81		0.006923	
	Glass fiber	65997-17-3	21.12		0.180509	
	Non halogen fire retardant	NA	0.01		0.000085	
	BT core	105391-33-1 25722-66-1 9003-36-5 21645-51-2 7440-50-8	43.38		0.370761	
Solder mask	147-14-8 7727-43-7 7631-86-9 14807-96-6 112-15-2 34590-94-8 103429-90-9 64742-94-5 25551-13-7	8.98		0.076750		

Revision History

The following table shows the revision history for this document.

Date	Version	Description of Revisions
02/01/2013	1.0	Xilinx Initial Release

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